


开放计算
技术沙龙

OAI 技术规范与应用

Jan. 28th, 2021 | Beijing 主办方: OCP中国社区

 **Alibaba Group**
阿里巴巴集团

 **Baidu** 百度

 **Cambricon**
寒武纪

 **CoreRaiin**
睿芯科技

 **Enflame**
燃源科技

 **Enflame**
燃源科技

 **inspur** 浪潮

 **intel**

 **京东云**

 **Microsoft**

 **平安科技**
PINGAN TECHNOLOGY

 **平安科技**
PINGAN TECHNOLOGY



Summary (Jan. 28th, Beijing)

- Open computing experts from Baidu/Inspur/Intel/Enclave/Microsoft delivered **5** keynote speeches
- **7** companies participated in the salon and joined the open discussion —
Alibaba/PingAn Technology/JD Cloud & AI/Cambricon/Corerain/Iluvatar CoreX/Biren Technology
- Focusing on **4** hot topics in the field of OAI, arranged for a **2-hour** open discussion
- Onsite sign-in **23** people meanwhile **10** people participate online, **12** companies were invited in total

The agenda of OAI Specification and Application Salon				
Time	Topic	Speaker	Entity	Title
14:00-14:05	Opening	Wilson Guo	Inspur Electronic Information	Sr. Technology Director, Technology R&D Dept.
14:05-14:20	The key value of OAI in the industrialization of AI technology & OAI liquid cooling solution	Zhenghui Wu	Baidu	Senior Architect
14:20-14:35	Inspur AI Open Platform	Gavin Wang	Inspur Electronic Information	Director System Architect
14:35-14:50	Habana interconnection solution in silicon and system level architecture for AI training usages	Michael Ma	Intel	Habana Technical director for Greater China
14:50-15:05	Break			
15:05-15:20	OAM and distributed Solution for AI training	Jidong Du	Enclave	Director System Architect
15:20-15:35	Open Platform and Tools for AI	Tingting Qin	Microsoft	Senior Researcher
15:35-17:30	Open Discussion	All	All	
17:30-20:00	Dinner			

Summary (Jan. 28th, Beijing)

Attendees discussed the value and application scenarios of OAI projects, major issues at present, and next actionable items and expectation for the OAI 2.0 standard.

- The range of OAM/UBB design spec is too broad to follow and design an AIPU accordingly. The ASIC developers has contacted OAI leaders to discuss the specification usage guide.
- AI chips are developing fast. To apply OAI to multiple AI cards, multiple systems and racks in the future, further OAI specification could involve in AIPU compiler, ASIC architecture and the software stack to decouple the hardware and software for users.
- The AI application environment is complex, and it is necessary to establish a performance evaluation test suite covering from ASICs, UBB boards, systems, and even to racks.



Meeting
Venue

Registration
&
Participants
badge





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Baidu



Inspur



Intel



Enflame



Microsoft

Keynotes
&
Open
Discussion



Rest Period





OAI

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THANK YOU!